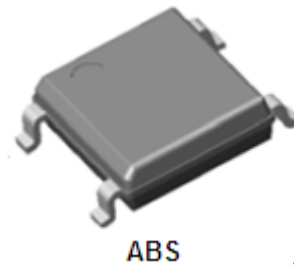
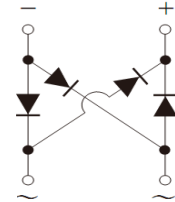


Features

- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High Surge Current Capability
- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- High temperature soldering guaranteed 250 C/10 seconds at terminals



RoHS
COMPLIANT



Mechanical Data

- Case: ABS, Molded Plastic
- Terminals: Solder plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbol marking on body
- Mounting Position: Any

Major Ratings and Characteristics

| | |
|-------------|-----------------------------------|
| $I_{F(AV)}$ | 0.8A, 1.0A |
| V_{RRM} | 200 V to 1000 V |
| I_{FSM} | 35 A |
| I_R | 5 μA |
| V_F | 1.00V |
| T_J max. | 150 $^{\circ}$C |

Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}$ C unless otherwise specified.

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

| Items | Symbol | ABS2 | ABS4 | ABS6 | ABS8 | ABS10 | Unit |
|---|-----------------------|--|------|------|------|-------|----------------|
| Peak repetitive reverse voltage DC blocking voltage | V_{RRM} V_{DC} | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | $V_{R(RMS)}$ | 140 | 280 | 420 | 560 | 700 | V |
| Maximum average forward rectified current at T_A (See Fig.1) | $I_{F(AV)}$ | 0.8 ⁽¹⁾ 1.0 ⁽²⁾ | | | | | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load(JEDEC Method) | I_{FSM} | 35 | | | | | A |
| Thermal resistance from junction to lead | $R_{\theta JL}$ | 25 | | | | | $^{\circ}$ C/W |
| Thermal resistance from junction to ambient ⁽¹⁾ | $R_{\theta JA}$ | 80 | | | | | $^{\circ}$ C/W |
| Thermal resistance from junction to ambient ⁽²⁾ | $R_{\theta JA}$ | 62.5 | | | | | $^{\circ}$ C/W |
| Operating junction temperature range | T_J | -55 to +150 | | | | | $^{\circ}$ C |
| Storage temperature range | T_{STG} | -55 to +150 | | | | | $^{\circ}$ C |

Note 1: Mounted on glass epoxy PC board with 1.3mm² solder pad.

Note 2: Mounted on aluminum substrate PC board with 1.3mm² solder pad.

Electrical Characteristics ($T_A = 25^{\circ}$ C unless otherwise noted)

| Items | Test conditions | Symbol | ABS02~ABS10 | Unit |
|---------------------------------------|------------------|--------|---------------------|------|
| Instantaneous forward voltage per leg | $I_F=0.5A^{(3)}$ | V_F | 1.0 | V |
| Reverse current | $V_R=V_{DC}$ | I_R | $T_A=25^{\circ}$ C | 5.0 |
| | | | $T_A=125^{\circ}$ C | 500 |

Note: 3. Pulse test: 300 μ s pulse width, 1% duty cycle.



Characteristic Curves (TA=25 °C unless otherwise noted)

Fig.1 Forward Current Derating Curve

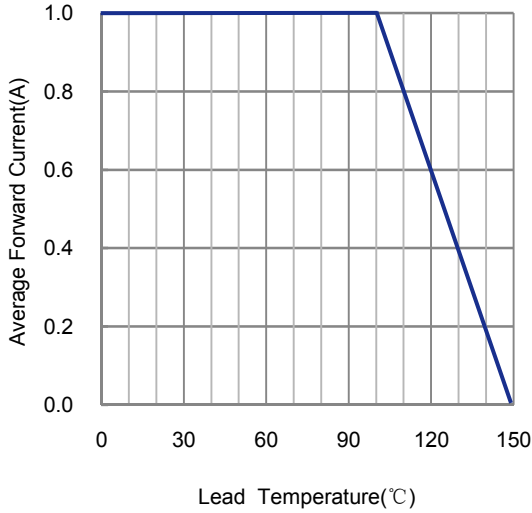


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

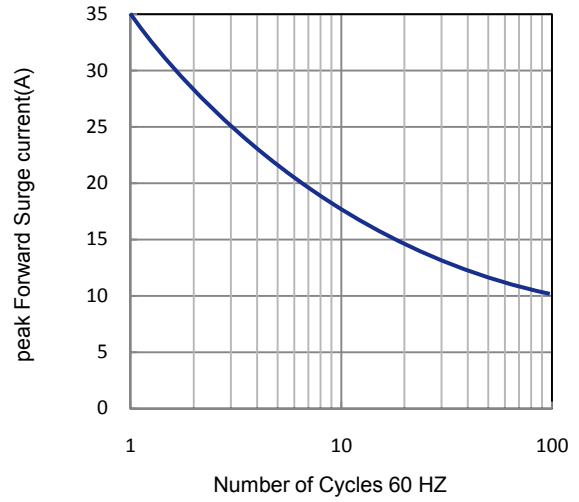


Fig.3 Typical Instantaneous Forward Characteristics

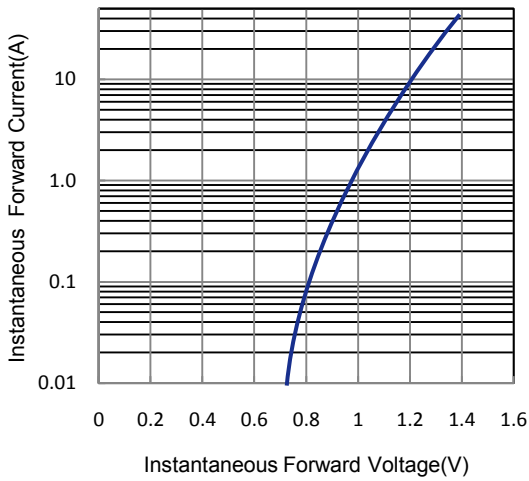
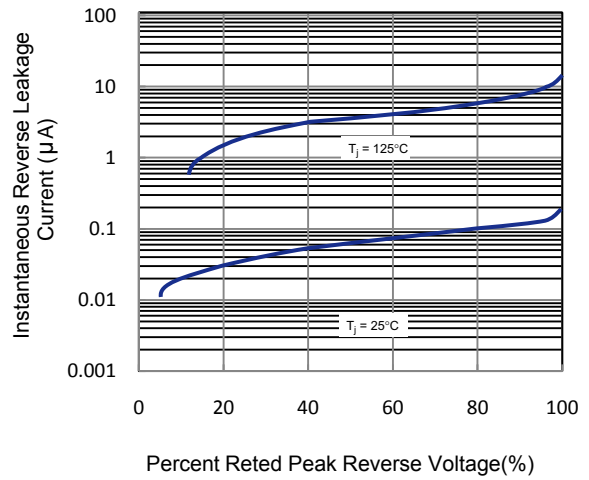
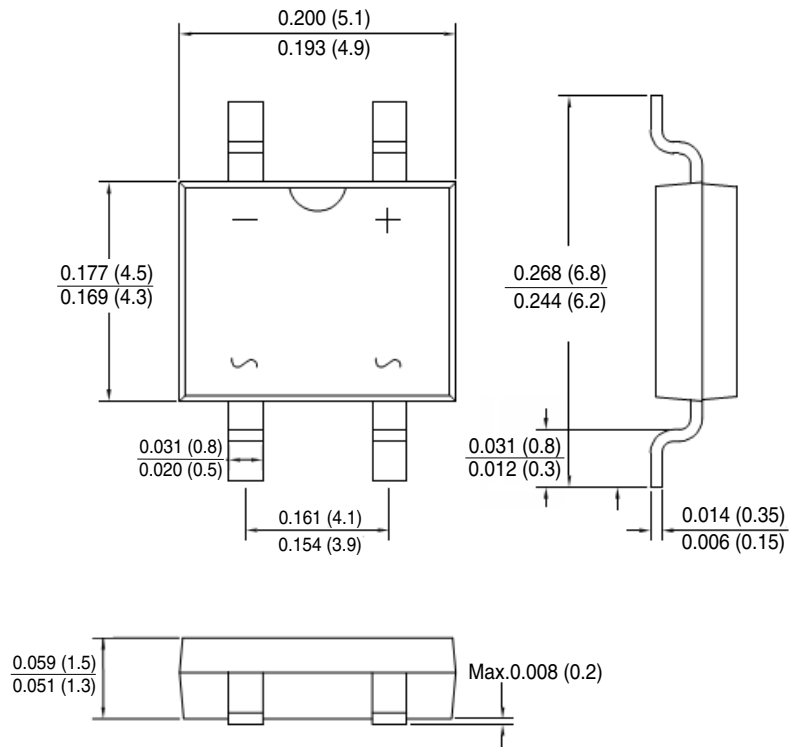


Fig.4 Typical Reverse Leakage Characteristics



Package Outline

ABS



Dimensions in inches and (millimeters)